

Part Number: XTNI11W

T-1 (3mm) Infrared Emitting Diode

Features

- Radial / Through hole package
- \bullet Reliable & robust
- Low power consumption
- Available on tape and reel
- \bullet RoHS Compliant







Absolute Maximum Ratings (T _A =25°C)		TNI (GaAs)	Unit		
Reverse Voltage	V_{R}	5	V		
Forward Current	\mathbf{I}_{F}	50	mA		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	1200	mA		
Power Dissipation	\mathbf{P}_{D}	90	mW		
Operating Temperature	$T_{\rm A}$	$\Gamma_{\rm A}$ -40 ~ +85			
Storage Temperature	Tstg	$-40 \sim +85$	°C		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds				
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds				

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T _A =25°C)		TNI (GaAs)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	1.2	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	1.6	V
Reverse Current (Max.) (V _R =5V)	I_R	10	μА
Wavelength of Peak Emission CIE127-2007*(Typ.) (I _F =20mA)	λP	940*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle \lambda$	50	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	90	pF

	Part Number	Emitting Material	Lens-color	Radiant Intensity (Po=mW/sr) CIE127-2007* @20mA		(Po=n CIE12'	Intensity 1W/sr) 7-2007* 0mA	Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.	min.	typ.		
	XTNI11W GaAs Water Cle		5	9	18	31	0.40*	200	
		GaAs	GaAs Water Clear	3*	7*	12*	24*	940*	30°

*Radiant Intensity value and wavelength are in accordance with CIE127-2007 standards.

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XDSB2496 V2-X Layout: Maggie L.







TNI







Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



I.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of $260^{\circ}C$ 2.Peak wave soldering temperature between $245^{\circ}C \sim 255^{\circ}C$ for 3 sec

2. Peak wave soldering temperature between 245° C ~ 255° C for (5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above 85°C. 4.Fixtures should not incur stress on the component when mounting and during soldering process.

during soldering process. 5.SAC 305 solder alloy is recommended.

6. No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on forward voltage or radiant intensity / luminous flux),

the typical accuracy of the sorting process is as follows:

- 1. Radiant Intensity / Luminous Flux: +/-15%
- 2. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters



PACKING & LABEL SPECIFICATIONS



RoHS Complia Made in China

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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
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